Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1		method with (stent prosthesis prostheses implant scaffold) with (electroform electroplat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/25 08:38
L2	13555	stainless adj steel with (bar mandrel stent)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/25 08:39
L4	2133	stainless adj steel with (bar mandrel stent) with (copper gold tantalum tin platinum)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/25 08:39
L5	402	stainless adj steel with (bar mandrel stent) with (copper gold tantalum tin platinum) same (coat coating cover covered electroplat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/25 08:41
L6	147	stainless adj steel with (bar mandrel stent) with (copper gold tantalum tin platinum) with (coat coating cover covered electroplat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2007/01/25 08:41
L7	64	stainless adj steel with (stent) with (copper gold tantalum tin platinum) with (coat coating cover covered electroplat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR ·	ON	2007/01/25 08:41
L8	84	stainless adj steel with (implant prosthesis stent) with (copper gold tantalum tin platinum) with (coat coating cover covered electroplat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2007/01/25 08:48
L9	2523	(205/80,97,102,118,129,170,182).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/25 08:49
L10	0	L9 and (coat cover plate plating plated surround) with stent with copper with steel	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/25 08:49
L11	1	(coat cover plate plating plated surround) with stent with copper with steel	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/25 08:49

L12	0	l9 and (coat cover plate plating plated surround electroplat\$3) with stent with copper with steel	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/25 08:50
L13	0	l9 and (deposit\$3 coat cover plate plating plated surround electroplat\$3) with stent with copper with steel	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/25 08:50
L14	4	I9 and (deposit\$3 coat cover plate plating plated surround electroplat\$3) with stent with (copper steel gold tantalum platinum tin)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/25 08:53
L15	. 2	10/495567.app. 10/490736.app.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/25 08:55
L16	1	10/257407.app.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/25 08:55
S2	2	(("6027527") or ("5902475")).PN.	US-PGPUB; USPAT	OR	OFF	2007/01/24 16:15
53	. 1	10/502456.app.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/24 16:24
S4 .	2522	(205/80,97,102,118,129,170,182).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/24 16:26
S5	4114	((205/80,97,102,118,129,170,182) or (623/1.15)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/24 16:26
S6	1456	S5 and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/24 16:26
S7	232	S5 and copper same (thermoplastic resin polystyrene polyethylene)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/24 16:28

S8	33	S5 and copper same (thermoplastic resin polystyrene polyethylene) and steel with (anode cathode electroplat\$3 electrolytic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/24 16:30
S9	14	S5 and copper same (thermoplastic resin polystyrene polyethylene) and steel with (electroplat\$3 electrolytic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/24 16:32
S10	93	S5 and copper same (thermoplastic resin polystyrene polyethylene) same (electroplat\$3 electrolytic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR ·	ON	2007/01/24 16:33
S11	2	("5902475").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/24 16:37
S12	201097	watanabe.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/24 16:37
S13	713	watanabe-eiji.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/24 16:38
514		eiji-watanabe.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/24 16:37
S15	1	watanabe-eiji.in. and stent	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/24 16:38
S16	117	S5 and stent with (plating electroplating electrolytic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/24 16:42
S17		S5 and stent with (radipopaque radiopacity gold platimun tantalum) with intracranial	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/24 16:42

S18	2126	stent with (radipopaque radiopacity gold platimun tantalum)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/24 16:43
S19	449	stent with (radipopaque radiopacity gold platimun tantalum) and (plating electrolytic electroplating eletroptiae electroplated plated)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/24 16:44
S20	14	stent with (radipopaque radiopacity gold platimun tantalum) and (plating electrolytic electroplating eletroptiae electroplated plated) with copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/24 16:52
S21	17	stent same (radipopaque radiopacity gold platimun tantalum) same (plating electrolytic electroplating eletroptiae electroplated plated) same copper same steel	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/24 16:53
S22	20	(stent implant prosthesis prostheses scaffold) same (radipopaque radiopacity gold platimun tantalum) same (plating electrolytic electroplating eletroptiae electroplated plated) same copper same steel	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/24 17:05
S23	30	("4343048" "4733665" "5366504" "5421955" "5443498" "5443500" "5449373" "5464419" "5649952").PN. OR ("6019784").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/01/24 16:54
S24	780	(stent implant prosthesis prostheses scaffold) same (radipopaque radiopacity gold platimun tantalum tin copper steel) same (plating electrolytic electroplating eletroptiae electroplated plated)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/24 17:06
S25	113	(stent implant prosthesis prostheses scaffold) same (radipopaque radiopacity gold platimun tantalum tin copper steel) same (plating electrolytic electroplating eletroptiae electroplated plated) and S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/24 17:06
S26	41	(stent implant prosthesis prostheses scaffold) same (radipopaque radiopacity gold platimun tantalum tin copper steel) same (plating electrolytic electroplating eletroptiae electroplated plated) and S5 and (resist thermoplastic resin)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/24 17:11
S27	37	(stent implant prosthesis prostheses scaffold) same (radipopaque radiopacity gold platimun tantalum tin copper steel) same (plating electrolytic electroplating eletroptiae electroplated plated) same (dissolve degrade deteriorate solvent remove)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/25 08:33